



JICTECH LCD (HONGKONG) CO.,LTD
DONGGUAN JICTECH LCD CO.,LTD
PROFESSIONAL LCM SUPPLIER

PRODUCT SPECIFICATION FOR LCD MODULE

Model NO.:JT035VBHVCS-A2

Specification Ver.: 01

APPROVAL FOR SPECIFICATIONS ONLY

APPROVAL FOR SPECIFICATIONS AND SAMPLE

CUSTOMER :

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1. GENERAL SPECIFICATION

1.1 Introduction

The JT035VBHVCS-A2 is a color active matrix Thin Film Transistor (TFT) Liquid Crystal Display (LCD) that uses amorphous silicon (a-Si) TFT as a switching device. This model is composed of a single 3.5 inches transmissive type main TFT-LCD panel. The resolution of the panel is 320[RGB]x480 pixels and can display up to 65K color.

1.2 Feature

- Using IPS panel. Viewing Direction POL.
- FOG and backlight assembly module.
- MIPI interface.

1.3 Application

- Display terminals for digital products. Industrial control Etc.

1.4 General Specification

| No. | | Specification | Note |
|-----|--------------------------|---|------|
| 1 | LCD Size | 3.5inch | - |
| 2 | Panel Type | a-Si TFT active matrix | - |
| 3 | Resolution | 320RGB(H) x 480(V) pixel | - |
| 4 | Display Mode | Normally Black | - |
| 5 | Display Number of Colors | 16.7M | - |
| 6 | Viewing Direction | ALL:00 Clock | - |
| 7 | Contrast Ratio | 700 | - |
| 8 | Luminance | 350cd/m ² | - |
| 9 | Module Size | 54.48mm ± 0.2(H) x 84.71mm ± 0.2(V) x 2.05mm ± 0.2(T) | - |
| 10 | Active Area | 48.96mm(H) x 73.44mm(V) | - |
| 11 | Pixel pitch | 0.051(H) x 0.153(V) | - |
| 12 | Driver IC | ST7796S | - |

| | | | |
|----|-------------------------|---------------------|---|
| 13 | Light Source | 6LEDs White | - |
| 14 | Interface | MIPI | - |
| 15 | Operating Temperature | -20~70 (Max. scope) | - |
| 16 | Storage Temperature | -30~80 (Max. scope) | - |
| 17 | Total Power dissipation | VCC=2.8-3.3V | - |
| 18 | Weight | TBD g | |

3. ABSOLUTE MAXIMUM RATINGS

| Parameter of absolute maximum ratings | Symbol | Min | Max | Unit |
|---------------------------------------|--------|------|---------------|------|
| Operating temperature | Top | -20 | 70 | °C |
| Storage temperature | Tst | -30 | 80 | °C |
| Humidity | RH | 60°C | 90%(Max60 °C) | RH |

4. ELECTRICAL CHARACTERISTICS

4.1. DC Characteristics

| Parameter of DC characteristics | Symbol | Min | Typ | Max | Unit |
|---------------------------------|--------|---------|-----|---------|------|
| Supply voltage for logic | VDD | 2.5 | 2.8 | 3.3 | V |
| Input Current | Idd | - | 25 | 36 | mA |
| Input voltage 'H' level | VIH | 0.7VDD | - | VDD | V |
| Input voltage 'L' level | VIL | VSS | - | 0.3VDD | V |
| Output voltage 'H' level | VOH | VDD-0.4 | - | VDD | V |
| Output voltage 'L' level | VOL | VSS | - | VSS+0.4 | V |

4.2. Backlight Characteristics

| Item of backlight characteristics | Symbol | Min. | Typ. | Max. | Unit | Condition |
|-----------------------------------|---------------------------|--------|------|--------|------|-----------|
| Forward voltage | V | 18.0 | 18.6 | 19.2 | V | If=20mA |
| LED circuit | 10 LEDs serial connection | | | | | |
| Chromaticity | x | 0.2800 | - | 0.3400 | - | If=20mA |
| White CIE (x, y) | y | 0.2700 | - | 0.3000 | - | |

Using condition: constant current driving method $I_f = \text{Single led } 20\text{mA} (+/-10\%)$.

5. INTERFACE DESCRIPTION

5.1. LCM PORT:

| Pin No. | Symbol | I/O | Description | When not in use |
|---------|--------|-----|--|-----------------|
| 1 | GND | P | System ground. | |
| 2 | LEDA | P | Power supply Anode input for backlight. | |
| 3 | LEDK | P | Power supply Cathode input for backlight. | |
| 4 | GND | P | System ground. | |
| 5 | D0N | I | Data Lane 0 | |
| 6 | D0P | I | Data Lane 0 | |
| 7 | GND | P | System ground. | |
| 8 | CLKN | I | MIPI-DSI CLOCK | |
| 9 | CLKP | I | MIPI-DSI CLOCK | |
| 10 | GND | P | System ground. | |
| 11 | RESET | I | Reset input signal. | |
| 12 | TE | P | FMARK | |
| 13 | IOVCC | P | I/O Voltage Power supply for LCM(1.8-3.3V) | |
| 14 | VCI | P | Power supply for LCM(2.8-3.3V) | |
| 15 | GND | P | System ground. | |

Note: The voltage power of the interface logic pin depend on “IOVCC” and “GND”.

6. ELECTRO-OPTICAL CHARACTERISTICS

| Item of electro-optical characteristics | Symbol | Condition | Min | Typ | Max | Unit | Remark | |
|---|----------------|---|-------|-----|-------|-------|--------|--------|
| Contrast ratio | CR | Viewing normal angle $\theta = \phi = 0^\circ$ If=40mA TC=25°C | 700 | - | - | - | Note 1 | |
| Surface sLuminance | Lv | | - | 350 | - | Cd/m2 | Note 2 | |
| Luminance uniformity | δ WHITE | | 80 | - | - | % | Note 3 | |
| Response time | Tr+Tf | | - | 30 | - | ms | Note 4 | |
| Viewing angle range | θ | Center (CR \geq 10) | 3:00 | - | 80 | - | degree | Note 5 |
| | | | 9:00 | - | 80 | - | | |
| | | | 6:00 | - | 80 | - | | |
| | | | 12:00 | - | 80 | - | | |
| Module Chromaticity CIE (x, y) | White | Viewing normal angle $\theta = \phi = 0^\circ$ | x | - | 0.309 | - | - | Note6 |
| | | | y | - | 0.332 | - | | |
| | Red | | x | - | 0.660 | - | | |
| | | | y | - | 0.325 | - | | |
| | Green | | x | - | 0.277 | - | | |
| | | | y | - | 0.568 | - | | |
| | Blue | | x | - | 0.145 | - | | |
| | | | y | - | 0.072 | - | | |
| NTSC Ratio | S | - | - | 70% | - | - | Note7 | |

*Note: All above side data are based on JICTECH following condition.

Note1. Contrast Ratio (CR) is defined mathematically by the following formula. For more information see FIG 1.

$$\text{Contrast Ratio} = \frac{\text{Average Surface Luminance with all white pixels (P1, P2, P3, P4, P5)}}{\text{Average Surface Luminance with all black pixels (P1, P2, P3, P4, P5)}}$$

Note2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 1.

$$L_v = \text{Average Surface Luminance with all white pixels (P1, P2, P3, P4, P5)}$$

Note3. The uniformity in surface luminance (δ WHITE) is determined by measuring luminance at each test position 1 through 5, and then dividing the maximum luminance of 5 points luminance by minimum luminance of 5 points luminance. For more information see FIG 1.

$$\delta \text{ WHITE} = \frac{\text{Minimum Surface Luminance with all white pixels (P1, P2, P3, P4, P5)}}{\text{Maximum Surface Luminance with all white pixels (P1, P2, P3, P4, P5)}}$$

Note4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 2.

Note5. Viewing angle is the angle at which the contrast ratio is greater than 2. For TFT module the contrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.

Note6. CIE (x, y) chromaticity ,The x,y value is determined by screen active area position 5. For more information see FIG 1.

Note7: NTSC ratio : For more information see FIG 4.

$$\text{NTSC ratio} = \frac{\text{Area of RGB triangle}}{\text{Area of NTSC triangle}}$$

Note8. For Viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope. Series Instruments. For contrast ratio, Surface Luminance, Luminance uniformity and CIE , the testing data is base on BM-7 photo detector.

Note9. For TFT transmissive module, Gray scale reverse occurs in the direction of panel viewing angle

FIG.1. Measuring method for Contrast ratio,surface luminance, Luminance uniformity,CIE (x,y) chromaticity

A : 5 mm

B : 5 mm

H,V : Active Area

Light spot size =5mm, 500mm distance from the

LCD surface to detector lens

measurement instrument is luminance meter BM-7.

or DMS 803.

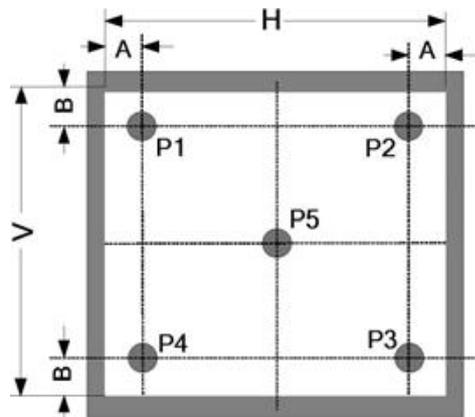


FIG. 2. The definition of Response Time

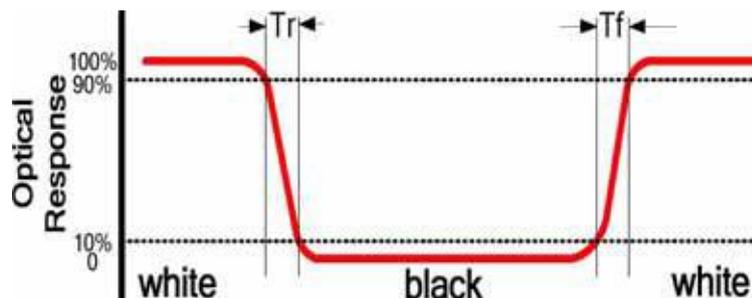


FIG. 3. The definition of viewing angle

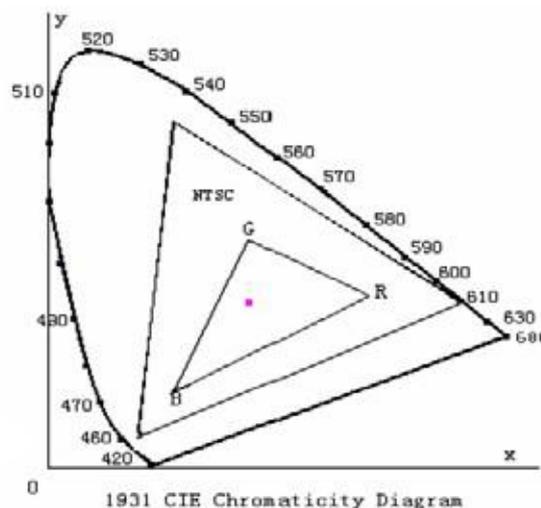
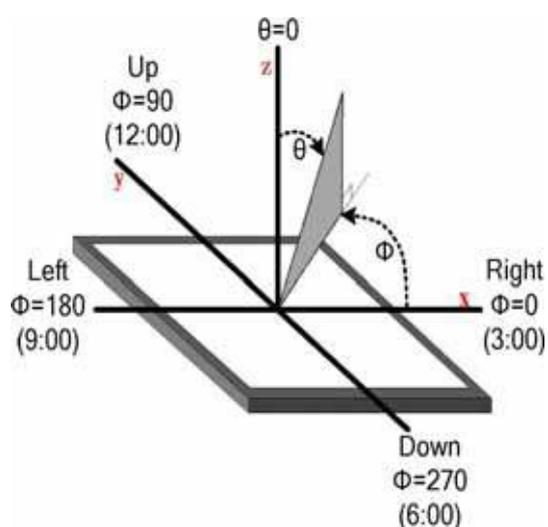


Fig.4. 1931 CIE chromaticity diagram

7.RELIABILITY TEST CONDITONS

| No. | Test Item | Content of Test | Test Conditions |
|-----|----------------------------|--|--|
| 1 | High Temperature Storage | Endurance test of high temperature for a long time. | 80±2°C48H |
| 2 | Low Temperature Storage | Endurance test of low temperature for a long time. | -30±2°C48H |
| 3 | High Temperature Operation | Endurance test of electrical stress (Voltage & Current) and the thermal stress to the element. | 70±2°C48H |
| 4 | Low Temperature Operation | Endurance test of electrical stress (Voltage & Current) and the thermal stress to the element. | -20±2°C48H |
| 5 | Thermal shock | Endurance test of low and high temperature cycles.(air to air) | -20±2°C(30min)→+25±2°C(30min)→+70(30min)±2°C,10 cycl |
| 6 | ESD test | ESD test | Voltage:±6kv/±4kv R: 200Ω C: 150pF Air/Contact discharge, 5 points each 1 times |

7.RELIABILITY TEST CONDITONS

| No. | Test Item | Content of Test | Test Conditions |
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| 1 | High Temperature Storage | Endurance test of high temperature for a long time. | 80±2°C48H |
| 2 | Low Temperature Storage | Endurance test of low temperature for a long time. | -30±2°C48H |
| 3 | High Temperature Operation | Endurance test of electrical stress (Voltage & Current) and the thermal stress to the element. | 70±2°C48H |
| 4 | Low Temperature Operation | Endurance test of electrical stress (Voltage & Current) and the thermal stress to the element. | -20±2°C48H |
| 5 | Thermal shock | Endurance test of low and high temperature cycles.(air to air) | -20±2°C(30min)→+25±2°C(30min)→+70(30min)±2°C,10 cycl |
| 6 | ESD test | ESD test | Voltage:±6kv/±4kv R: 200Ω C: 150pF Air/Contact discharge, 5 points each 1 times |

Note:

- 1) When making the low temperature test, not to dewy.
- 2) Driving condition for operation test. Power Supply Voltage for Logic System Failure Judgment Criterion After the above mentioned test.(For Environmental Test, after 2 hours in room temperature.) There should not be conspicuous failure of display quality and appearance.
- 3) Contrast ratio should be 50% of the initial contrast ratio.
- 4) There should not have any abnormality of function.

LIFE TIME

| Item | Description |
|------|---|
| 1. | Functions, Performance, appearance, etc. shall be free from remarkable deterioration within 20,000 hours under ordinary operating and storage conditions room temperature ($25\pm 10^{\circ}\text{C}$) , normal humidity($40\pm 20\%RH$),and in area not exposed to direct sun light. |

8.INSPECTION CRITERIA

1. The sampling plan and scheme
MIL-STD-105E,General II level standard single sampling inspection level

2. Acceptable standards (AQL)

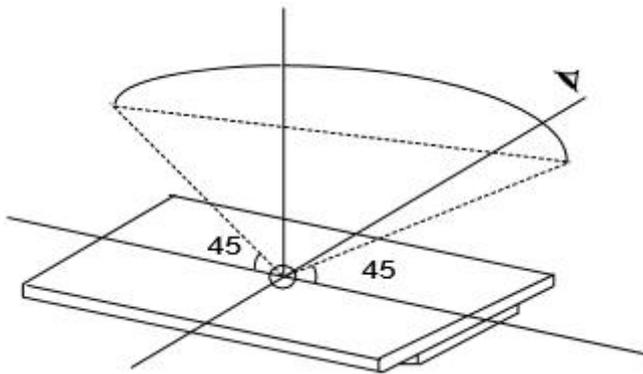
main defects(MAJ) : 0.65

minor defects(MIN) : 1.5

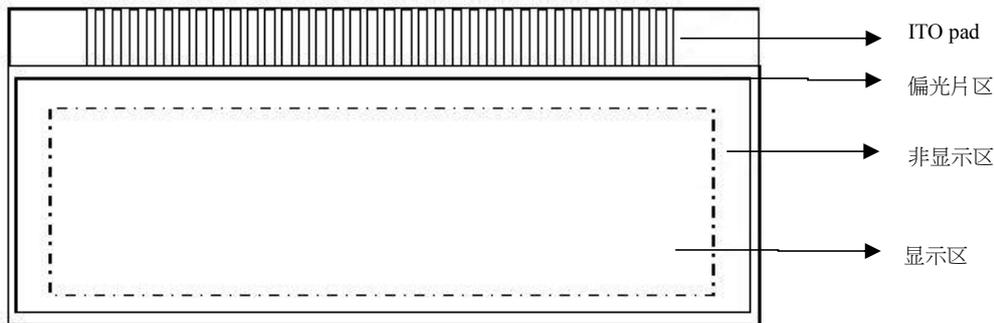
3. Test conditions and method

8.1 Temperature $25\text{ }^{\circ}\text{C} \pm 5\text{ }^{\circ}\text{C}$,humidity $45 \pm 20\%$,enough light (40W fluorescent lamp,about 40cm),the sightdistance is 30cm

8.2 $0^{\circ}\sim 45^{\circ}$ left and right 45° , upper and bottom $0^{\circ}\sim 45^{\circ}$



8.3 Area definition



8.4 Intensive definition: there are less than two points or two lines within 10mm^2 , known as dense.

8.5 If the standards, specifications is not consistent with technical requirements,the product data sheet shall be prevailed

8.6 For the LCD that more than 80pcs /tool ,use A standard if customers have special requirements

Distance between unqualified points $\geq 5\text{mm}$

8.1 Classification of defects

The main defects (MAJ): the product has lost its function or can't reach the specification requirements in terms of performance parameters, or because of the size of the problem caused by the inability to assemble.

Slight defects (MIN): appearance can't meet the standard requirements, but no other effects

8.7 Test voltage, refer the usage requirements of jig set and the product design requirements, compare with approval sample

8.7.1 By default, LCD voltage external can be adjusted, the standard performance and voltage are controlled as below: when LCD driver voltage $\leq 5V$, controlled as $\pm 0.2V$, when LCD driver voltage $> 5V$, controlled as $\pm 0.3V$, for COG type, if the VOP is lower than 10V, controlled as $\pm 0.2V$, if VOP is higher than 10V, controlled $\pm 0.3V$.

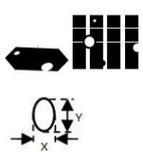
8.7.2 Customers have special requirements for fixed voltage products, the internal circuit adjustment to ensure that the display effect, and if necessary, develop a lower limit of the sample

8.2 Defect items and acceptance standards

Mechanical size: to meet technical specifications drawings, according to the main defect judgment

Electrical properties

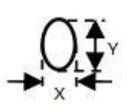
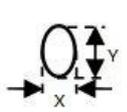
| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|---------------------------------|--|--|--------------|
| 8.7.3 | Missing segment | Horizontal / vertical missing segment, lack of icons, lack of stroke | NG | MAJ |
| 8.7.4 | No display, no action | No display in normal connection | NG | MAJ |
| 8.7.5 | Display error, abnormal display | According to the normal scanning program, the ICON is inconsistent with order and requirements or displayed randomly | NG | MAJ |
| 8.7.6 | Wrong angle view | The angle view is inconsistent with the design requirements (or samples) | NG | MAJ |
| 8.7.7 | Contrast depth | Under normal display, the overall contrast is too deep or slight, and the voltage deviation exceeds the standard | Refer to the 4.9.1 item voltage standard control | MAJ |
| 8.7.8 | Cross Talk | Display crosstalk shall not exceed limit sample | Reference limit sample | MAJ |
| 8.7.9 | Extra display | Display icons, strokes, rows, columns, lines, etc. that should not be displayed at work | Reference dot and line standard | MIN |
| 8.7.10 | PI dot | Local black spots or white spots appear when change image | Pause screen visible, reference point, line standard, reference sample during changing image | MIN |

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|--|--|---------------------------------|--------------|
| 8.7.11 | Pinhole and bumps defect  $d=(X+Y)/2$ | At work, the pattern is incomplete or out of shape | Reference dot and line standard | MIN |

LCD appearance

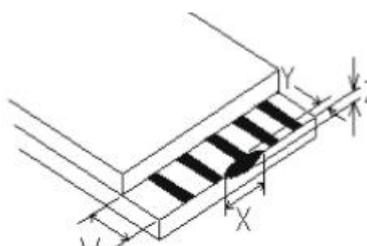
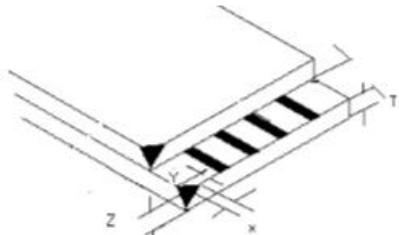
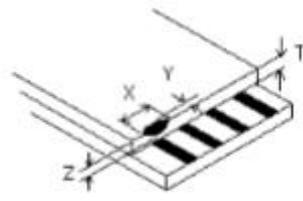
Dot, line (just for V.A area control)

8.7.12

| Item | size(mm) | QTY' | Defect grade |
|--|----------------------------|------|--------------|
| | | A1 级 | |
| Spot (black dot, sundries,stab, scratch)  $d=(X+Y)/2$ | $d \leq 0.15$ | 3 | MIN |
| | $d \leq 0.20$ | 3 | |
| | $0.20 < d \leq 0.25$ | 1 | |
| | $0.25 < d \leq 0.30$ | 0 | |
| | $0.30 < d$ | 0 | |
| Polarizer bubble  $d=(X+Y)/2$ | $d \leq 0.15$ | 3 | MIN |
| | $0.30 < d \leq 0.20$ | 2 | |
| | $0.50 < d \leq 0.30$ | 0 | |
| | $0.80 < d$ | 0 | |
| Line (black line, white line,debris, stab, scratches, water wave) | $L \leq 2.00, W \leq 0.02$ | 2 | MIN |
| | $L \leq 2.00, W \leq 0.03$ | 2 | |
| | $L \leq 3.00, W \leq 0.05$ | 0 | |
| | $L \leq 3.00, W \leq 0.10$ | 0 | |

LCD broken and crack,(aim at the product that without bezel and the LCD corner directly exposed including COG, heat seal connector (FPC),LCD+BL type, and the product with bezel ,if it won't affect the function and reliability after assembly or the breakage and crack covered by bezel ,it can be acceptable, L is the length of the breakage side,W is the width of ITO,T is the thickness for single LCD , H is the width together with plastic frame)

8.7.13

| Item | Acceptable criteria | | Defect grade | |
|---|---------------------|----------------------|--------------|--|
| Conductive foot position crack  | (mm) | A1 级 | MIN | |
| | X | $\leq 1/8L$ | | |
| | Y | $\leq 1/4W$ | | |
| | Z | $\leq t$ | | |
| acceptable QTY' | 2 | | | |
| corner crack (ITO pin)  | X | $X+Y \leq 3.5$ | MIN | |
| | Y | | | |
| | Z | $\leq t$ | | |
| | acceptable QTY' | 1 | | |
| Item | Acceptable criteria | | Defect grade | |
| Sealing surface collapse (external collapse)  | X | $\leq 1/8L$ | MIN | |
| | Y | invisible in VA area | | |
| | Z | $\leq t$ | | |
| | acceptable QTY' | 2 | | |

| Item | Acceptable criteria | | Defect grade |
|--|--|-------|--------------|
| Convex glass, cutting defect, burrs, W, is ITO width | X | ≤3.0 | MIN |
| | Y | ≤1/6W | |
| | Z | / | |
| | acceptable QTY' | 1 | |
| | The for the burrs, controlled according to the specifications of dimension tolerances | | |
| fissure | non-directional and progressive cracks is not allowed. The fissure in the interior is NG and the fissure outward is acceptable(refer to the breakage criteria) | | MAJ |

Polarizer

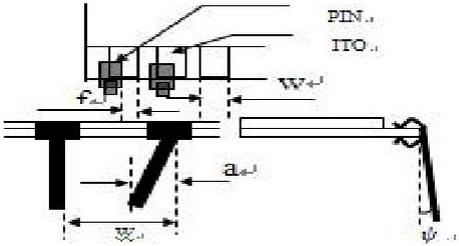
| Items | Description | Acceptance criteria | Defect grade |
|---|---|---|--------------|
| Slice oblique / serrated | Polarizer does not cover frame lines, or over tolerances | 1. non-ITO pad area can be cut 2. in general, A1, A2, A3 are controlled by tolerances for polarizer attaching, A0, A* controlled by vertical view until can observe black edge | MIN |
| water wave | To observe wave water phenomenon on the polarizer surface against the light | Refer to sample | MIN |
| The protective film is difficult to tear, fall off and tilt | / | 1.for peel off tape, if 3 times can bring up protective film, it's qualified. 2. the protective film on LCD front can't be tilted, obvious dirt or polarizer dirt can't be | MIN |

| | | | |
|--------------------------------------|---|--|-----|
| | | allowed 3., the protection film tilting will affect COG/FOG crimping, all reject 4. do not allow the protective film to fall off | |
| Polarizer is attached to the reverse | The angle is reversed and the bottom or surface is reversed | rejection | MAJ |
| contamination | polarizer contamination | obvious contamination is not allowed | MIN |
| direction | the range of angle view, background difference | Refer to the sample and keep in line with the same batch | MIN |
| bubble, concave-convex dot | There is air or bubbles caused by ink between polarizer and glass | for concave-convex dot, need to refer to sample | MIN |

Other inspection items

| Items | Description | Acceptance criteria | Defect grade |
|----------------------------|---|--|--------------|
| Rainbow | 1pcs product with two or more colors | refer to sample | MIN |
| Leakage | Vacuum bubble, sealing is not full, liquid crystal is not filled, etc. | NG | MAJ |
| Protective film | There is no protective film on the polarizer, and obvious contamination on the surface is not allowed | NG | MIN |
| PIN part no and spec | the part no , specifications, length, span, angle, shape for PIN foot should be consistent with drawing | NG | MAJ |
| Appearance | The PIN QTY' can't match, poor contact; sealed and UV glue on ITO is not completely cured, without sealing glue. | NG | MAJ |
| | PIN glue leakage, glue breakage, glue exceeds LCD, glue exceeds polarizer, If customer request special, the amount of glue should be judged as a serious defect | NG | MIN |
| | there is glue on PIN , PIN loose, deformed, skewed, and oxidized | NG | MIN |
| Peel-off tape | Missing attach, wrong position, crooked, peel off tape can not peel off protective film | NG | MIN |
| Identification and marking | already requested add Identification and marking on protection film or LCD footstep | The content is consistent with the requirement | MIN |

| | | | |
|--|--|---|--|
| | | If the code can be identified at once, it is judged to be qualified | |
|--|--|---|--|

| Items | Description | Acceptance criteria | Defect grade |
|-----------------------|--|--|--------------|
| Surface silk printing | After make silk printing, attach polarizer on LCD surface, observe there are Linear bubble phenomenon | refer to sample | MIN |
| PIN position |  <p>f=PIN 错位宽度 shift width , w=ITO pad 宽度 width</p> | PIN crooked : $a \leq 1/3w$, $\psi \leq \pm 5^\circ$ | MIN |

Back-light

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|-----------------------------|---|---|--------------|
| 8.7.14 | LED no display, wrong color | LED no display, the color is not consistent with the sample or specifications | NG | MAJ |
| 8.7.15 | color difference | it's different with sample when display, and also different with drawing after measuring | NG | MIN |
| 8.7.16 | Luminance difference | the luminance is different with sample when display and different with drawing also after measuring | If the deviation of the specifications is not indicated on the drawings, it shall be controlled according to the range of $\pm 15\%$ of the brightness for sample | MIN |
| 8.7.17 | Nonuniform | the uniformity is different with spec when display | if it's out of spec, reject, the uniformity that don't request on drawing should be controlled as more than 75% | MIN |

| | | | | |
|--------|---------|--|--------------------------------|-----|
| 8.7.18 | Scratch | it happen contamination .scratch ,dot and line defect when display | Refer to dot and line standard | MIN |
| 8.7.19 | Flicker | flicker phenomenon can't be allowed when display | NG | MAJ |

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|-----------------------------|---|--|--------------|
| 8.7.20 | B/L perk | PCB B/L must be very close to attach with PCB B/L | Backlight tilt no more than 0.5mm is allowed | MIN |
| 8.7.21 | Componen ts taken off | the components on light guide is taken off | NG | MAJ |
| 8.7.22 | Date code | The code is inconsistent with the sample or drawing | NG | MIN |

PCB/PCBA

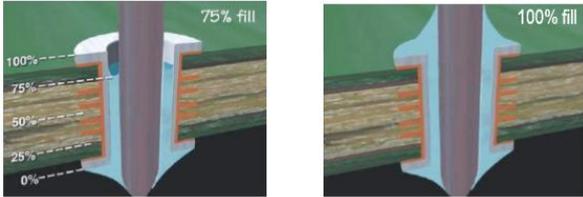
| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|---------------------|---|---------------------|--------------|
| 8.7.23 | Glue sealing defect | <p>1) there is a bonding line in the round white mark, the circuit is exposed or the soldering plate is exposed more than 1 places;</p> <p>2) the height of sealing glue exceeds the requirement of spec; (no special requirement is controlled by 1.5mm)</p> <p>3) the sealing glue shall be in the white mark, the maximum shall not exceed the mark radius outside 2mm;</p> <p>4) there is obvious linear traces on the glue surface, and the pinholes penetrate through the wafers;</p> <p>5) the needle hole diameter of the glue surface >0.25mm and has extra objects;</p> <p>6) glue permeates to the opposite side of PCB</p> | reject | MIN |

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|-----------------------------|---|--|--------------|
| 8.7.24 | PCB appearance | 1) the surface of gold plate is oxidized or with dirt 2) gold is not golden, bright 2)there is bubbles after reflow soldering 3) warping and perking 4) green pitting, oxidation, corrosion | reject | MIN |
| | | Green oil is faded,scratch or expose copper | Green oil pen repair. The diameter is 1.3mm on the line, and the diameter on the non-line is 2.6mm, allowing 10 places. | |
| | | Glue area with glue | diameter≤2.0mm,2pcs allowed | |
| | | Silk color,oil color,silk content,silk form | 样品 sample | MIN |
| 8.7.25 | Components error or missing | The components on the PCBA is not consistent with BOM. The direction is wrong and the polarity is the opposite | NG | MAJ |
| 8.7.26 | Part no | part no or version is different with spec | 拒收 reject | MAJ |

SMT/SOLDERING

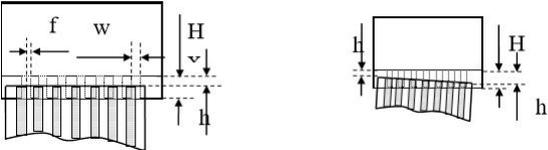
| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|------------------|---|---------------------|--------------|
| 8.7.27 | Soldering defect | 1)cold welding, false welding, missing welding , cracking of tin, tin is not dissolved etc.; 2) non welding area with tin ball or tin slag | NG | MAJ |
| 8.7.28 | DIP device | DIP devices, buttons, connectors and other devices are floating high and skew | NG | MIN |
| 8.7.29 | The shape of | The soldering point shall be recessed and shall be not allowed excess solder and inadequate | acceptable | MIN |

| | | | | |
|--|-----------------|----------------------|--|--|
| | soldering point | tin and tin tip etc. | | |
|--|-----------------|----------------------|--|--|

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|---|---|--|--------------|
| 8.7.30 | Components foot exposed | for the plug type welding device, after soldering, cut off the foot | The height should be controlled in 0.5mm~2.0mm, cannot hurt the tin ball surface and excess welding cause device foot disappear | MIN |
| NO. | Items | Description | Acceptance criteria | Defect grade |
| 8.7.31 | The tin on the soldering vias is not reasonable | <p>Metal soldering vias, solder joints, minimum tin penetration shall not exceed 25% of the plate thickness (i.e., the tin content is not less than 75% of the plate thickness as picture 1); the required pore size of the particular product shall be 100% filled, as shown in Figure 2</p>  <p style="text-align: center;">图 1 图 2</p> | <p>general, the tin content is not less than 75% of the plate thickness, and the special requirement is that the product exceeds 100% of the tin content</p> | MIN |
| 8.7.32 | Appearance defect | The residual rosin is yellowish brown or charred | NG | MIN |
| 8.7.33 | Welding pinhole | happen spot Blowhole during welding process | $D \leq 0.2\text{mm}$, 1pcs allowed | MIN |

Hot seal

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|-------------|---|------------------------------------|--------------|
| 8.7.34 | part no and | Specifications for Zebra paper, FPC, etc. | Refer to the BOM sheet or drawings | MAJ |

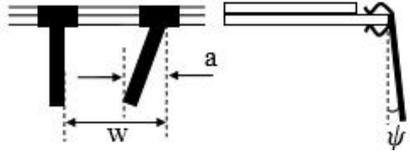
| | | | | |
|--------|------------------------|---|---|-----|
| | spec | | | |
| 8.7.35 | dimension and position | The size of heat pressing material should be within the range of drawing specification  | $f \leq 1/3W, h \leq 1/4H$, And meet the drawing size requirements | MIN |

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|---------------------------------------|---|---------------------|--------------|
| 8.7.36 | objects happened during heat pressing | The foreign objects in the heat pressing area, and it is not in the open position, can not cause short circuit; the foreign objects is smaller than the 50% pressing area | acceptable | MIN |
| 8.7.37 | fold trail | FPC or zebra paper fold to damage is not allowed | NG | MIN |
| 8.7.38 | FPC 外观 | scratches, breakage, gold plate oxidized, stains | refer to sample | MIN |

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|-------|--|---|--------------|
| 8.7.39 | burrs | FPC with convex or concave in the edge | 不伤及线路情况下 $\leq 2.0\text{mm}$ 控制 In the case without damaging the circuit controlled as $\leq 2.0\text{mm}$ | MIN |

Connector and other parts

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|--------------|--|---------------------|--------------|
| 8.7.40 | part no/spec | The part no / specification must meet BOM list and design requirements, and the position shall be within the drawing specification | acceptable | MAJ |
| 8.7.41 | position | Welding reverse | NG | MAJ |
| 8.7.42 | order | The order of the first PIN and the PIN shall be consistent with the specifications of the product drawings | acceptable | MIN |

| | | | | |
|--------|------------------|---|---|-----|
| 8.7.43 | contamination | External device and PIN foot are stained with solder flux, and the sealing glue shall not be attached to the PIN end of the connector | NG | MIN |
| 8.7.44 | PIN out of shape | <p>PIN connector, PIN bending, skew phenomenon</p>  | <p>1) Pin out of shape is no more than 1/3 PIN thickness (if with socket, must guarantee connection well), can't allow PIN bent and bottom layer leakage</p> <p>2) PIN shift, $a \leq w/3$, $\psi \leq 5^\circ$, don't affect assembly, acceptable</p> | MIN |

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|--------------------------|--|------------------------------|--------------|
| 8.7.45 | PIN oxidation | PIN oxidation | NG | MIN |
| 8.7.46 | The via hole are blocked | Plug type connectors are not allowed to have a hole to plug the deformation phenomenon; with the latch of the lock should be able to tie the external connector lock (the matching pin to ensure that the matching plug and lock good) | NG | MIN |
| 8.7.47 | others | Other additional parts shall be consistent with drawings and technical requirements | if not affect function, pass | MIN |

LCM APPEARANCE

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|--------------------------------------|---|---------------------|--------------|
| 8.7.48 | the appearance of connector material | <p>FPC, gold plate or zebra paper, the FPC end that connect with LCD or PIN exposed copper or leaking substrate;</p> <p>There are breakage, stain, or FPC, FFC, COF, zebra paper and other peripheral materials already fold to almost damaged (except original design);</p> <p>FPC, PCB gold plate with a sticky tin greater than 2/3 PIN wide;</p> <p>FPC, FFC and other material stab, fold trail exceeds limited sample</p> | NG | MIN |

| 8.7.49 | 补强带 不良 | The adhesive tape must be completely covered and the protect circuits (such as zebra paper, FFC, FPC, etc.) can't exceed PIN area, and the black tape at the IC position shall be able to effectively shade the IC position | acceptable | MIN |
|--------|-----------------------------------|---|--|--------------|
| 8.7.50 | reinforcing board or glue | After heat pressing, attach strong adhesive tape or play reinforcing glue according to technical specifications to protect all circuits, missing attachment is not allowed and must keep surface flat | acceptable | MIN |
| 8.7.51 | appearance stain | the labels or marks of rework product are not clean well, obvious stains (dust, finger prints), residual glue, etc. | In general, the batch of stains can not be acceptable normally | MIN |
| 8.7.52 | assembly objects | the contamination(like dot or line) caused by B/L or diffusion | refer to dot/line standard | MIN |
| NO. | Items | Description | Acceptance criteria | Defect grade |
| 8.7.53 | three proof pain | For the products that need three proof paint, the painting position must be correct, the pin and the test position, the gold plate can not be painted, the special location can not be exposed, and the thickness meets the design requirements | NG | MIN |
| 8.7.54 | product identification | part no and batch No (including Stickers / silk screen / inkjet) should be consistent with the requirements of the document, not blurred, leakage, paste, leak spray, bar code scanning defect | NG | MIN |
| 8.7.55 | Component identification | The component mark is not clear, the measurement value is consistent with the document request | allowed | MIN |
| 8.7.56 | Breakage of electronic components | components with hiatus or broken | NG | MAJ |
| 8.7.57 | assembly position | after assembly, upper and bottom 、 left and right of LCD shift and overall shift | refer to drawing and sample | MIN |
| 8.7.58 | mixed material | The same batch of products mixed with different part no | NG | MAJ |

| | | | | |
|--------|---------------------|--|--|-----|
| | s | | | |
| 8.7.59 | TP assembly objects | there is TP assembly objects like fog shape | if it's invisible when display,pass it,others refer to dot/line standard | MIN |
| 8.7.60 | Socket or pin skew | upper and bottom , left and right shift | refer to drawing tolerance or sample | MIN |
| 8.7.61 | glue sealing defect | PIN glue exceeds polarizer 2) IC bonding glue with the hole that inner circuit or IC can be visible | NG | MIN |

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|----------------------|--|--|--------------|
| 8.7.62 | overall structure | The overall mechanism assembly must be consistent with the assembly drawings | 1) assembly skew, shift,(light guide LCD, TP, etc.), NG 2) bezel out of shape need to refer to limit sample | MIN |
| 8.7.63 | PIN heated to injure | In the process of welding ,pin is heated to injure | if it cause PIN not in a line,reject | MIN |

PACKAGING

| NO. | Items | Description | Acceptance criteria | Defect grade |
|--------|---------------------------|--|---------------------|--------------|
| 8.7.64 | Identification error | the par no on the label, order number, date code is not consistent with each other | NG | MAJ |
| 8.7.65 | shortage | The QTY' of identification is not consistent with actual QTY' | NG | MAJ |
| 8.7.66 | Package safety compliance | Packing meets ocean transportation requirements, anti-static, moisture-proof and so on | NG | MAJ |

Others

If there are items that not be stipulated and concessions to release, subject to the agreement and the limit of the sample

9 PRECAUTION FOR USE OF LCD MODULE

9.1. Handling Precautions

- 1) The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 2) If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 5) If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:

--Isopropyl alcohol 异丙醇

--Ethyl alcohol 酒精

Solvents other than those mentioned above may damage the polarizer.

Especially, do not use the following:

--Water 水

--Ketone 芳香剂

- 6) Do not attempt to disassemble or process the LCD module.

9.2. Assembling Precautions

- 1) When mounting the LCD module make sure that it is free of twisting, warping, and distortion. Distortion has great influence upon display quality. Also keep the stiffness enough regarding the outer case.
- 2) Please handle the LCD module by its side.
- 3) NC terminal should be open. Do not connect anything.
- 4) If the logic circuit power is OFF, do not apply the input signals.
- 5) To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - Be sure to ground the body when handling the LCD module.
 - Tools required for assembly, such as soldering irons, must be properly grounded.
 - To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
 - The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
- 6) Be careful when treating the glass panel because it has very sharpened edge.

9.3. Storage Precautions

- 1) When storing the LCD module, avoid exposure to direct sunlight or to the light of fluorescent lamps and high temperature/high humidity. Whenever possible, the LCD module should be stored in the same conditions in which they were shipped from our company.
- 2) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets or a current flow in a high-humidity environment.

9.4. Design Precautions

The absolute maximum ratings represent the rated value beyond which LCD module can not

- 1) exceed. When the LCD modules are used in excess of this rated value, their operation characteristics may be adversely affected.
- 2) To prevent the occurrence of erroneous operation caused by noise, attention must be paid to satisfy VIL, VIH specification values including taking the precaution of using signal cables that are short.
- 3) The LCD exhibits temperature dependency characteristics. Since recognition of the display becomes difficult when the LCD is used outside its designated operating temperature range, be sure to use the LCD within this range. Also keep in mind that the LCD driving voltage levels necessary for clear displays will vary according to temperature.
- 4) We recommend that power supply lines (VDD) have over-current protection line. (Fuse etc. Recommend Value:0.5A)
- 5) Sufficiently notice the mutual noise interference occurred by peripheral devices.
- 6) To cope with EMI, take measures basically on outputting side.
- 7) When installing an LCD module, fasten it at the LCD panel.
- 8) The display panel is made of general float glass which is not guaranteed for strength. So please consider about following.
 - Do not subject panel to a mechanical shock by dropping directly.
 - Do not let case to touch to panel directly.

Others

- 1) Liquid crystal solidifies under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the LCD module is subjected to a strong shock at a low temperature.
- 2) If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.
- 3) To minimize the performance degradation of the LCD module's resulting from destruction caused by static electricity, etc., exercise care to avoid touching the following section when handling this module: LCD's Terminal electrode sections.
- 4) Optimum voltage to obtain best contrast value depending on products. Therefore voltage adjustment with electric volume is required in each display.
- 5) Precaution for disposal of LCD module. When disposal of LCD module, ask specialization company of industrial waste which is permitted by the government. When burn up LCD module, obey the law of environmental hygienics.